



Vishay Siliconix Leadframe Modification

DESCRIPTION OF CHANGE: As part of the Vishay Siliconix continuous improvement program, we would like to announce the slight modification to the leadframes used on select SSOT23 products. Physically, a dambar is being added between the leads on the frame to prevent movement of the bond wire landing pads during the mold operation (see Fig 1).

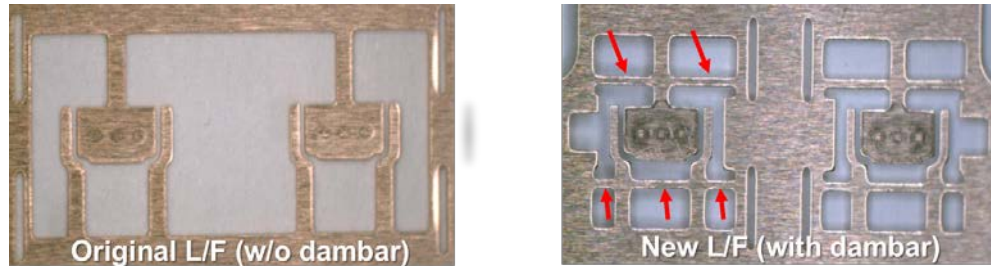


Fig 1

The dambar is trimmed prior to the tin plating of the leads, so there will be no exposed copper due to this change. While there will be a minor change to the look of the part (Fig 2), the change will not affect any dimensions called out in the Package Outline Drawing.

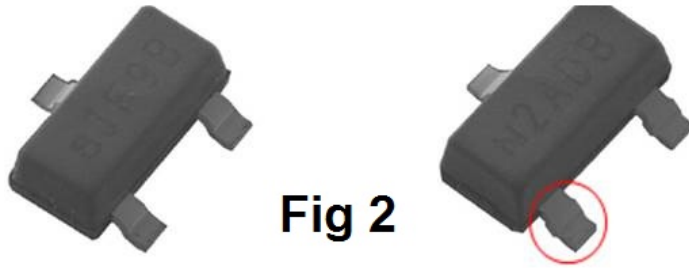


Fig 2

CLASSIFICATION OF CHANGE: Change in direct material design

REASON FOR CHANGE: Package robustness to prevent the movement of the bond wire landing pads during the mold operation

EXPECTED INFLUENCE ON QUALITY/RELIABILITY/PERFORMANCE: There will be no effect on quality, reliability or electrical performance as a result of this leadframe modification. There will be no changes to data sheets specifications or package dimensions.

PRODUCT CATEGORY: Low Voltage Power MOSFETs

AFFECTED PARTS: Refer to Table 1 on following page

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Advisory Product Change Notification



Product Group: Vishay Siliconix/ July 1, 2016/APCN-SIL-0132016 Rev 0

Table 1. AFFECTED PARTS

SI2300DS-T1-GE3	SI2308BDS-T1-GE3	SI2328DS-T1-E3	SI2392ADS-T1-GE3	SQ2351ES-T1_GE3
SI2301BDS-T1-E3	SI2309CDS-T1-E3	SI2328DS-T1-GE3	SI2392DS-T1-GE3	SQ2351ES-T1-GE3
SI2301BDS-T1-GE3	SI2309CDS-T1-GE3	SI2329DS-T1-GE3	SI2399DS-T1-GE3	SQ2360EES-T1-GE3
SI2301CDS-T1-E3	SI2312BDS-T1-E3	SI2333CDS-T1-E3	SMM2348ES-T1-GE3	SQ2361AEES-T1_GE3
SI2301CDS-T1-GE3	SI2312BDS-T1-GE3	SI2333CDS-T1-GE3	SQ2301ES-T1_GE3	SQ2361EES-T1-GE3
SI2301CDS-T1-GE3-S	SI2312CDS-T1-GE3	SI2333DDS-T1-GE3	SQ2301ES-T1-GE3	SQ2361ES-T1_GE3
SI2302ADS-T1-E3	SI2314EDS-T1-E3	SI2333DS-T1-E3	SQ2303ES-T1_GE3	SQ2362ES-T1_GE3
SI2302CDS-T1-E3	SI2315BDS-T1-E3	SI2333DS-T1-GE3	SQ2303ES-T1-GE3	SQ2389ES-T1_GE3
SI2302CDS-T1-GE3	SI2315BDS-T1-GE3	SI2334DS-T1-GE3	SQ2308BES-T1-GE3	SQ2398ES-T1_GE3
SI2302DDS-T1-GE3	SI2316BDS-T1-E3	SI2335DS-T1-E3	SQ2308CES-T1_GE3	SQ7002AK-T1-GE3
SI2303BDS-T1-E3	SI2316BDS-T1-GE3	SI2336DS-T1-GE3	SQ2308CES-T1-GE3	SY2301BDS-T1-E3
SI2303BDS-T1-GE3	SI2316DS-T1-E3	SI2337DS-T1-E3	SQ2308ES-T1-GE3	SY2302ADS-T1-E3
SI2303CDS-T1-E3	SI2316DS-T1-GE3	SI2337DS-T1-GE3	SQ2309ES-T1_GE3	SY2303BDS-T1-E3
SI2303CDS-T1-GE3	SI2318CDS-T1-GE3	SI2338DS-T1-GE3	SQ2309ES-T1-GE3	SY2309DS-T1-E3
SI2304BDS-T1-E3	SI2318DS-T1-E3	SI2342DS-T1-GE3	SQ2310ES-T1_GE3	SY2312DS-T1-E3
SI2304BDS-T1-GE3	SI2318DS-T1-GE3	SI2343CDS-T1-GE3	SQ2310ES-T1-GE3	SY2315BDS-T1-E3
SI2304DDS-T1-GE3	SI2319CDS-T1-GE3	SI2343DS-T1-E3	SQ2315ES-T1_GE3	SY2316DS-T1-E3
SI2304DDS-T1-GE3-S	SI2319DS-T1-E3	SI2343DS-T1-GE3	SQ2315ES-T1-GE3	SY2318DS-T1-E3
SI2305ADS-T1-E3	SI2319DS-T1-GE3	SI2347DS-T1-GE3	SQ2318AES-T1_GE3	SY2319DS-T1
SI2305ADS-T1-GE3	SI2321DS-T1-E3	SI2351DS-T1-E3	SQ2318AES-T1-GE3	SY2319DS-T1-E3
SI2305CDS-T1-GE3	SI2323CDS-T1-GE3	SI2351DS-T1-GE3	SQ2318ES-T1-GE3	SY2325DS-T1-E3
SI2305DS-T1-E3	SI2323DDS-T1-GE3	SI2356DS-T1-GE3	SQ2319ADS-T1_GE3	SY2328DS-T1-E3
SI2305DS-T1-GE3	SI2323DS-T1-E3	SI2365EDS-T1-GE3	SQ2319AES-T1_GE3	SY2335DS-T1-E3
SI2306BDS-T1-E3	SI2323DS-T1-E3-D	SI2366DS-T1-GE3	SQ2319ES-T1-GE3	SY2351DS-T1-E3
SI2306BDS-T1-GE3	SI2323DS-T1-GE3	SI2367DS-T1-GE3	SQ2325ES-T1_GE3	TN2404K-T1-E3
SI2307BDS-T1-E3	SI2324DS-T1-GE3	SI2369DS-T1-GE3	SQ2328ES-T1-GE3	TN2404K-T1-E3-D
SI2307BDS-T1-GE3	SI2325DS-T1-E3	SI2371EDS-T1-GE3	SQ2337ES-T1_GE3	TN2404K-T1-GE3
SI2307CDS-T1-E3	SI2325DS-T1-GE3	SI2372DS-T1-GE3	SQ2337ES-T1-GE3	V30434-T1-GE3
SI2307CDS-T1-GE3	SI2327DS-T1-E3	SI2374DS-T1-GE3	SQ2348ES-T1_GE3	V50389-T1-GE3
SI2307CDS-T1-GE3-S	SI2327DS-T1-GE3	SI2377EDS-T1-GE3	SQ2348ES-T1-GE3	V50396-T1_GE3
SI2308BDS-T1-E3				

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